



HM2907A

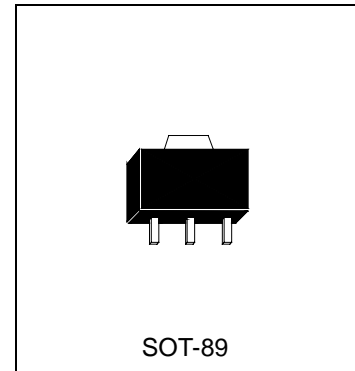
PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HM2907A is designed for general purpose amplifier and high speed, medium-power switching applications.

Features

- Low collector saturation voltage
- High speed switching
- For complementary use with NPN type HM2222A



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 1.2 W
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -60 V
 VCEO Collector to Emitter Voltage -60 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -600 mA

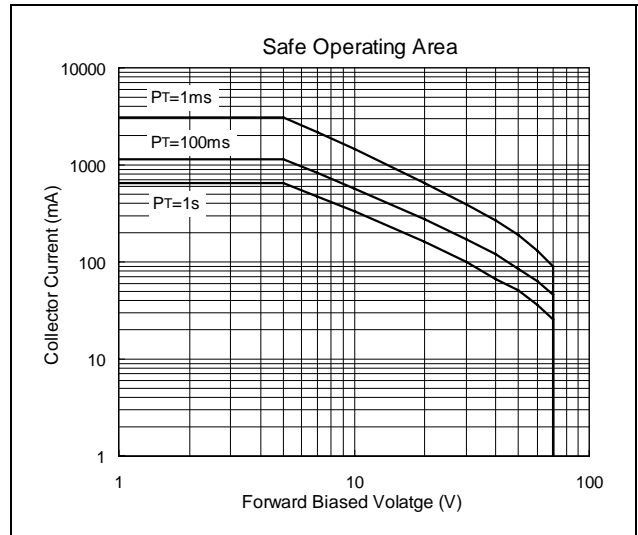
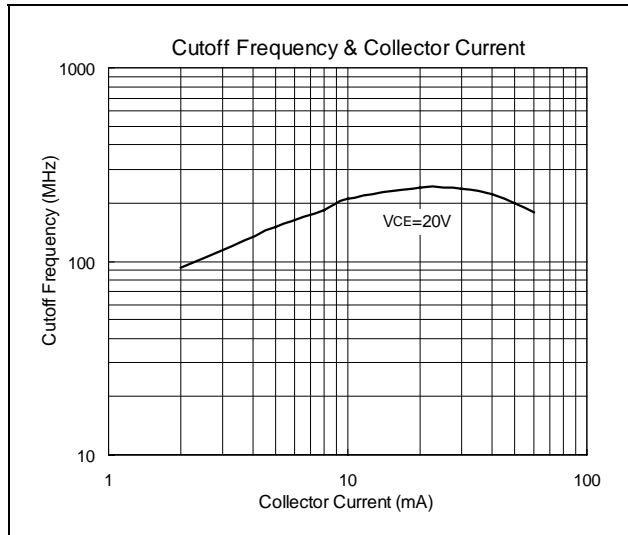
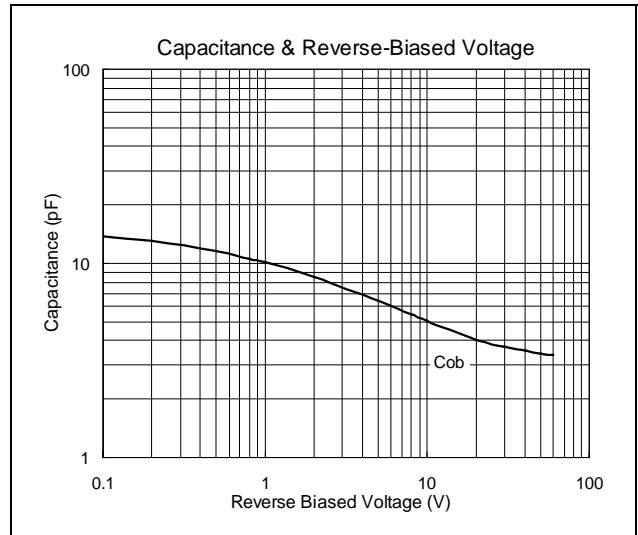
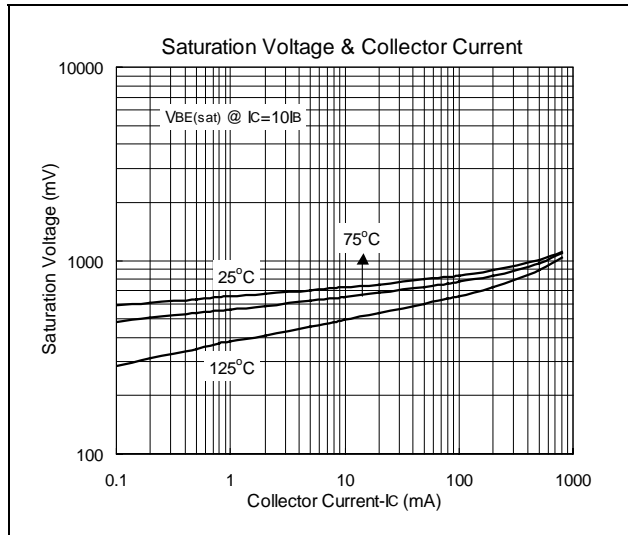
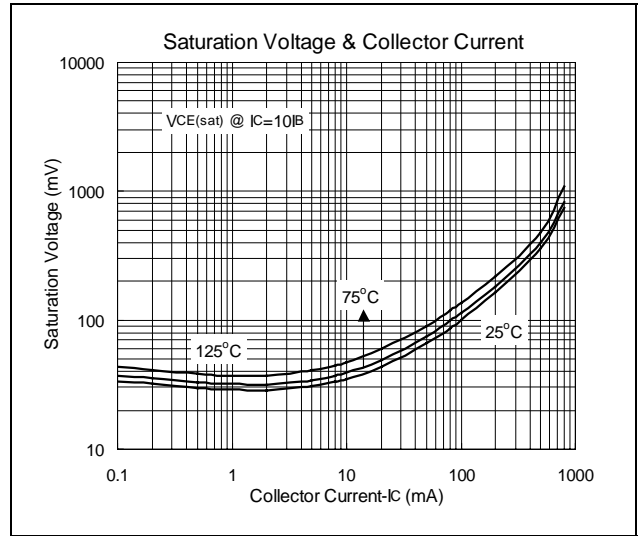
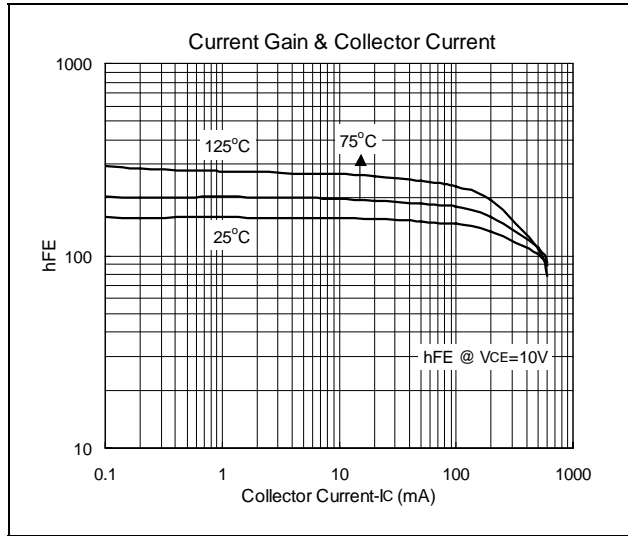
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-10uA
BVCEO	-60	-	-	V	IC=-10mA
BVEBO	-5	-	-	V	IC=-10uA
ICBO	-	-	-10	nA	VCB=-50V
ICEX	-	-	-50	nA	VCE=-30V, VBE=-0.5V
*VCE(sat)1	-	-0.2	-0.4	V	IC=-150mA, IB=-15mA
*VCE(sat)2	-	-0.5	-1.6	V	IC=-500mA, IB=-50mA
*VBE(sat)1	-	-	-1.3	V	IC=-150mA, IB=-15mA
*VBE(sat)2	-	-	-2.6	V	IC=-500mA, IB=-50mA
*hFE1	75	-	-		VCE=-10V, IC=-100uA
*hFE2	100	-	-		VCE=-10V, IC=-1mA
*hFE3	100	-	-		VCE=-10V, IC=-10mA
*hFE4	100	-	300		VCE=-10V, IC=-150mA
*hFE5	50	-	-		VCE=-10V, IC=-500mA
fT	200	-	-	MHz	VCE=-20V, IC=-50mA, f=100MHz
Cob	-	-	8.0	pF	VCB=-10V, f=1MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle ≤2%

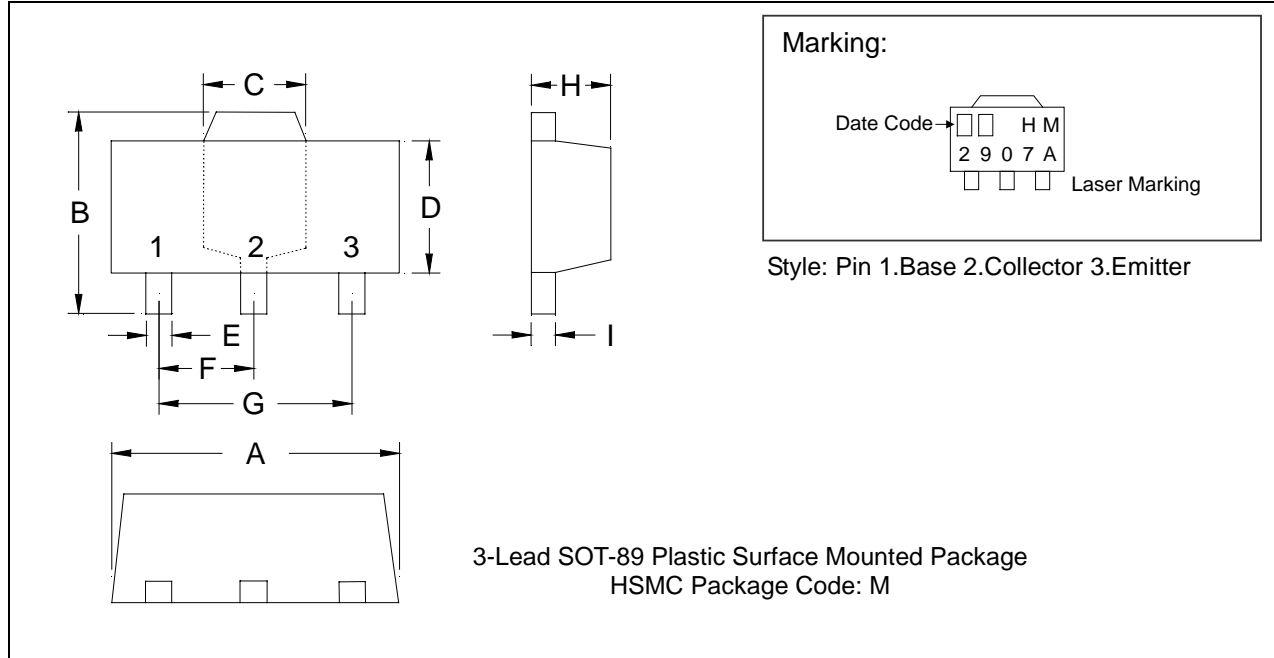


Characteristics Curve





SOT-89 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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